



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20180927002.2
Qualification of TI Mexico as an additional
Assembly Site for select devices
Change Notification / Sample Request

Date: September 28, 2018
To: PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,
PCN Team
SC Business Services

PCN Number:	20180927002.2		PCN Date:	Sept 28, 2018												
Title:	Qualification of TI Mexico as an additional Assembly Site for select devices															
Customer Contact:	PCN Manager	Dept:	Quality Services													
Proposed 1st Ship Date:	Mar 28, 2019	Estimated Sample Availability:	Date Provided at Sample request													
Change Type:																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
				<input type="checkbox"/>	Wafer Fab Process											
PCN Details																
Description of Change:																
Texas Instruments Incorporated is announcing the qualification TI Mexico as Additional Assembly Site for select devices listed in the "Product Affected" Section. Current assembly sites and Material differences are as follows.																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin</th> <th>Assembly Country Code</th> <th>Assembly Site City</th> </tr> </thead> <tbody> <tr> <td>Microchip Technology</td> <td>ALP</td> <td>THA</td> <td>Chachoengsao</td> </tr> <tr> <td>TI Mexico</td> <td>MEX</td> <td>MEX</td> <td>Aguascalientes</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City	Microchip Technology	ALP	THA	Chachoengsao	TI Mexico	MEX	MEX	Aguascalientes
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City													
Microchip Technology	ALP	THA	Chachoengsao													
TI Mexico	MEX	MEX	Aguascalientes													
Material Differences:																
	ALP	MEX														
Mount Compound	14M201001	4147858														
Mold compound	141002067	4211880														
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																
Reason for Change:																
Continuity of supply.																
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																
None																
Anticipated impact on Material Declaration																
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.													
Changes to product identification resulting from this PCN:																
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>ASO:</th> </tr> </thead> <tbody> <tr> <td>Microchip Technology</td> <td>Assembly Site Origin (22L)</td> <td>ASO: ALP</td> </tr> <tr> <td>TI Mexico</td> <td>Assembly Site Origin (22L)</td> <td>ASO: MEX</td> </tr> </tbody> </table>					Assembly Site	Assembly Site Origin (22L)	ASO:	Microchip Technology	Assembly Site Origin (22L)	ASO: ALP	TI Mexico	Assembly Site Origin (22L)	ASO: MEX			
Assembly Site	Assembly Site Origin (22L)	ASO:														
Microchip Technology	Assembly Site Origin (22L)	ASO: ALP														
TI Mexico	Assembly Site Origin (22L)	ASO: MEX														

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:



MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO:USA
(22L) AS0: MLA (23L) ACO: MYS

Product Affected:

AM26C31MDREP	AM26LV31ESDREP	V62/07647-01XE	V62/09602-01XE
AM26C32MDREP	AM26LV32EMDREP	V62/07648-01XE	V62/09603-01XE

Qualification Report

MMT Offload Qualification for SOIC Devices

Approve Date 24-Sep-2018

Product Attributes

Attributes	Qual Device: <u>AM26C32MDREP</u>	Qual Device: <u>UC1843AMDREP</u>	Qual Device: <u>UCC2801MDREP</u>	QBS Package Reference: <u>PCM1801U</u>	QBS Package Reference: <u>SN65HVD1780DR</u>	QBS Package Reference: <u>TL598CDR</u>	QBS Package Reference: <u>TPS2419DR</u>
Assembly Site	MEX	MLA	MLA	MLA	MLA	MEX	MEX
Package Family	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC	SOIC
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	SFAB	SFAB	TSMC WF2	DMOS5	SFAB	MIHO
Wafer Fab Process	IMPC60-80	JI-PWR1	IMP-PWR1	0.6-DPDM	LBC5X	JI1	LBC7

- QBS: Qual By Similarity

- Qual Devices AM26C32MDREP, UC1843AMDREP, UCC2801MDREP are qualified at LEVEL1-260CG

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>AM26C32MDREP</u>	Qual Device: <u>UC1843AMDREP</u>	Qual Device: <u>UCC2801MDREP</u>	QBS Package Reference: <u>PCM1801U</u>
AC	Autoclave 121C	96 Hours	1/77/0	1/77/0	1/77/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	1/77/0	-	-

Type	Test Name / Condition	Duration	Qual Device: <u>AM26C32MDREP</u>	Qual Device: <u>UC1843AMDREP</u>	Qual Device: <u>UCC2801MDREP</u>	QBS Package Reference: <u>PCM1801U</u>
HTSL	High Temp Storage Bake 170C	420 Hours	1/77/0	-	1/77/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	1/77/0	1/77/0	3/231/0
VM	Visual / Mechanical	(per mfg. Site specification)	1/328/0	1/328/0	1/328/0	3/328/0
WBP	Bond Pull	Wires	1/76/0	1/76/0	1/76/0	3/76/0
WBS	Ball Bond Shear	Wires	1/76/0	1/76/0	1/76/0	3/76/0

Type	Test Name / Condition	Duration	QBS Package Reference: <u>SN65HVD1780DR</u>	QBS Package Reference: <u>TL598CDR</u>	QBS Package Reference: <u>TPS2419DR</u>
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0
VM	Visual / Mechanical	(per mfg. Site specification)	3/328/0	3/328/0	3/328/0
WBP	Bond Pull	Wires	3/76/0	3/76/0	3/76/0
WBS	Ball Bond Shear	Wires	3/76/0	3/76/0	3/76/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/lscs/ti/legal/termsofsale.page>"

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com